



TO-247 物料成分表

Material Composition Data

构成部件 Sub-part(if yes)		构成成分 Composition	CAS编号 CAS No.	化学成分%
英文名称 English	重量(mg) Weight	英文名称 English		
Die	729.6	Si	7440-21-3	100.00%
Lead Frame	3040	Cu	7440-50-8	99.77%
		Fe	7439-89-6	0.1%
		P	7723-14-0	0.03%
		other	-	0.1%
Solder	3.04	lead	7439-92-1	95.50%
		silver	7440-22-4	2.50%
		tin	7440-31-5	2%
Al Ribbon	12.16	AL	7429-90-5	100%
Mold Compound	2286.08	Epoxy Resin	29690-82-2	10-20%
		Phenolic Resin	9003-35-4	1-5%
		Silica	60676-86-0	60-80%
		Carbon black	1333-86-4	0.1-1%
		Metal hydroxide	-	5-10%
Plating	9.12	Tin	7440-31-5	99.99%
Total	6080			

Notes: Lead in internal soft solder, ROHS exemption clause Annex 7a"lead in high melting temperature type solders" applied. Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, it is for guidance only and we cannot guarantee to its accuracy or completeness.